

L Number	Hits	Search Text	DB	Time stamp
1	46690	semiconductor adj wafer	USPAT; US-PGPUB	2004/10/20 13:10
2	11301	(semiconductor adj wafer) and alignment	USPAT; US-PGPUB	2004/10/20 13:10
3	2627	((semiconductor adj wafer) and alignment) and mark	USPAT; US-PGPUB	2004/10/20 14:14
4	* 19	((semiconductor adj wafer) and alignment) and mark) and 33/\$.ccls.	USPAT; US-PGPUB	2004/10/20 13:24
5	1	("5311061").PN.	USPAT; US-PGPUB	2004/10/20 13:31
6	559	(257/797).CCLS.	USPAT; US-PGPUB	2004/10/20 13:31
7	* 47	((semiconductor adj wafer) and alignment) and mark) and zeroth	USPAT; US-PGPUB	2004/10/20 14:15
8	8019	first adj mask	USPAT; US-PGPUB	2004/10/20 14:22
9	6072	(first adj mask) and (second adj mask)	USPAT; US-PGPUB	2004/10/20 14:22
10	4479	((first adj mask) and (second adj mask)) and semiconductor	USPAT; US-PGPUB	2004/10/20 14:22
11	2079	((first adj mask) and (second adj mask)) and semiconductor) and wafer	USPAT; US-PGPUB	2004/10/20 14:23
12	1804	((first adj mask) and (second adj mask)) and semiconductor) and wafer) and etch\$	USPAT; US-PGPUB	2004/10/20 14:23
13	1546	((first adj mask) and (second adj mask)) and semiconductor) and wafer) and etch\$) and deposit\$	USPAT; US-PGPUB	2004/10/20 14:26
14	1072	((first adj mask) and (second adj mask)) and semiconductor) and wafer) and etch\$) and deposit\$) and align\$	USPAT; US-PGPUB	2004/10/20 14:27
15	* 54	((first adj mask) and (second adj mask)) and semiconductor) and wafer) and etch\$) and deposit\$) and align\$) and concave	USPAT; US-PGPUB	2004/10/20 14:27

* viewed all